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FDT3612

100V N-Channel PowerTrench® MOSFET

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

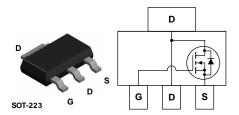
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\rm DS(ON)}$ specifications. The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

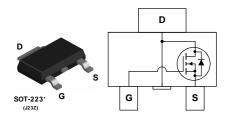
Applications

- DC/DC converter
- · Motor driving

Features

- 3.7 A, 100 V. $R_{DS(ON)}$ = 120 m Ω @ V_{GS} = 10 V $R_{DS(ON)}$ = 130 m Ω @ V_{GS} = 6 V
- · Fast switching speed
- Low gate charge (14nC typ)
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS(ON)}}$
- High power and current handling capability in a widely used surface mount package





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		100	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	3.7	А
	- Pulsed		20	
P _D	Maximum Power Dissipation	(Note 1a)	3.0	W
		(Note 1b)	1.3	
		(Note 1c)	1.1	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		−55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	42	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	12	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
3612	FDT3612	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	urce Avalanche Ratings (Note	2)		ı	I	I
W _{DSS}	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 50 \text{ V}$, $I_D = 3.7 \text{ A}$			90	mJ
I _{AR}	Drain-Source Avalanche Current				3.7	Α
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		106		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			10	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	2.5	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-6		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = 10 \text{ V}, \qquad I_D = 3.7 \text{ A}$ $V_{GS} = 6 \text{ V}, \qquad I_D = 3.5 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 3.7 \text{A}, T_J = 125^{\circ}\text{C}$		88 94 170	120 130 245	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$	10			Α
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 3.7 \text{ A}$		11		S
Dvnamio	Characteristics			I	I	I
C _{iss}	Input Capacitance	$V_{DS} = 50 \text{ V}, \qquad V_{GS} = 0 \text{ V},$ f = 1.0 MHz		632		pF
Coss	Output Capacitance			40		pF
C _{rss}	Reverse Transfer Capacitance	7		20		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, \qquad I_{D} = 1 \text{ A},$		8.5	17	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		2	4	ns
t _{d(off)}	Turn-Off Delay Time	7		23	37	ns
t _f	Turn-Off Fall Time	7		4.5	9	ns
Q_g	Total Gate Charge	$V_{DS} = 50 \text{ V}, \qquad I_{D} = 3.7 \text{ A},$		14	20	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V		2.4		nC
Q_{gd}	Gate-Drain Charge			3.8		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Source				2.5	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.5 \text{ A}$ (Note 2)		0.75	1.2	V

Notes

^{1.} $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 42°C/W when mounted on a 1in² pad of 2 oz copper



b) 95°C/W when mounted on a .0066 in² pad of 2 oz copper



c) 110°C/W when mounted on a minimum pad.

Typical Characteristics

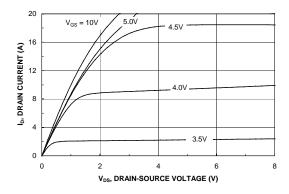


Figure 1. On-Region Characteristics.

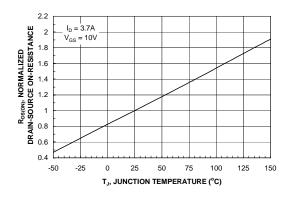


Figure 3. On-Resistance Variation with Temperature.

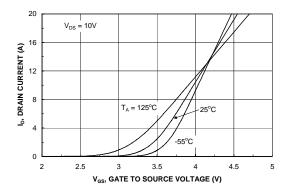


Figure 5. Transfer Characteristics.

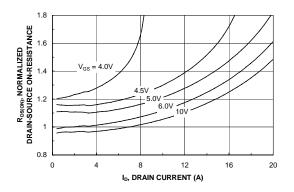


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

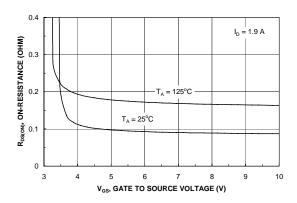


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

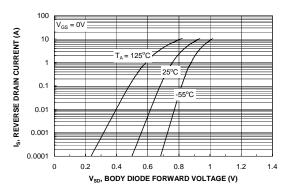
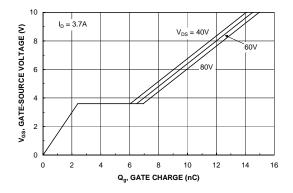


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



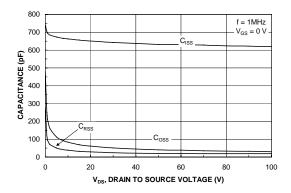


Figure 7. Gate Charge Characteristics.

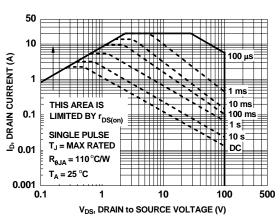


Figure 8. Capacitance Characteristics.

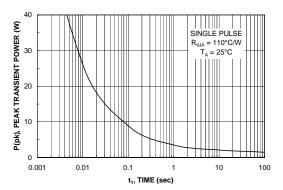


Figure 9. Maximum Safe Operating Area.



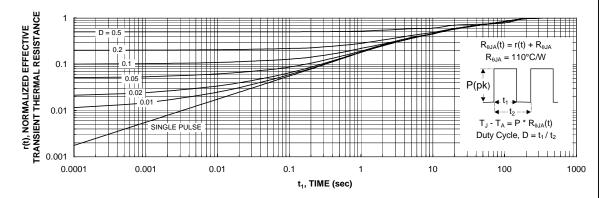
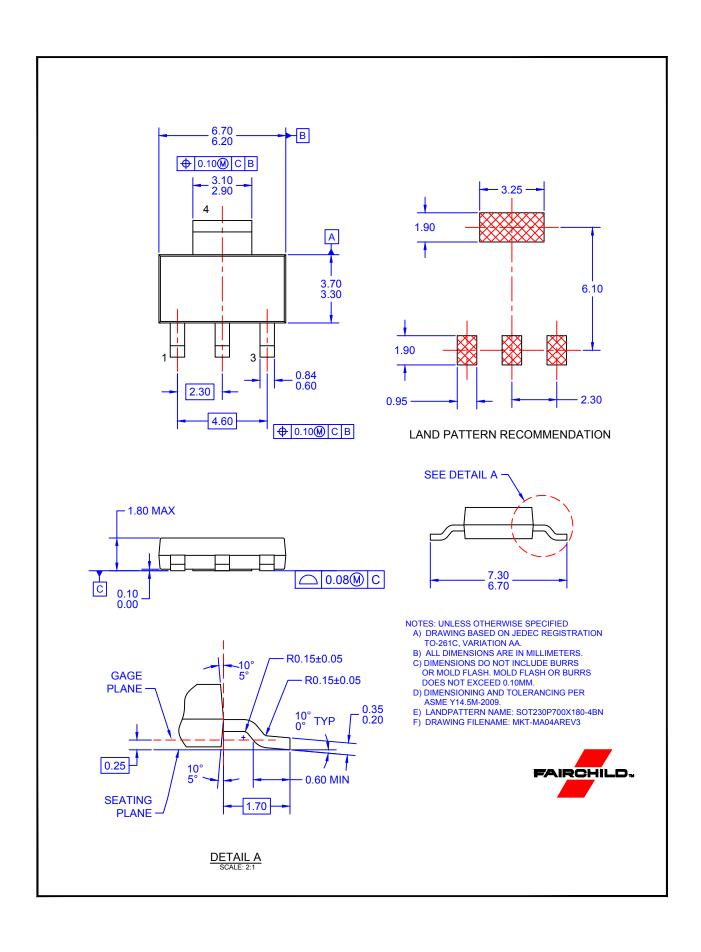


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.



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